NEC

Solid State Relay
OCMOS FET

PS7241E-1A

4-PIN SOP 400 V BREAK DOWN VOLTAGE NORMALLY OPEN TYPE 1-ch Optical Coupled MOS FET

–NEPOC Series–

DESCRIPTION

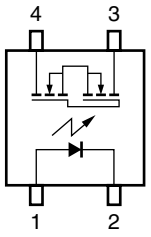
The PS7241E-1A is an optically coupled element that combines a GaAs infrared LED on the input side with a normally-open MOS FET on the output side to realize an excellent cost performance.

The small, thin package and high sensitivity of this element makes it ideal for battery-driven mobile devices, and its small offset voltage at power-on and good linearity are also make it suitable for controlling micro analog signals.

FEATURES

- Small and thin package (4-pin SOP, Height = 2.1 mm)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Low offset voltage
- Ordering number of taping product: PS7241E-1A-E3, E4, F3, F4
- Pb-Free product
- Safety standards
  - UL approved: No. E72422
<R>
  - BSI approved: No. 8241/8242

PIN CONNECTION
(Top View)



1. LED Anode
2. LED Cathode
3. MOS FET
4. MOS FET

APPLICATIONS

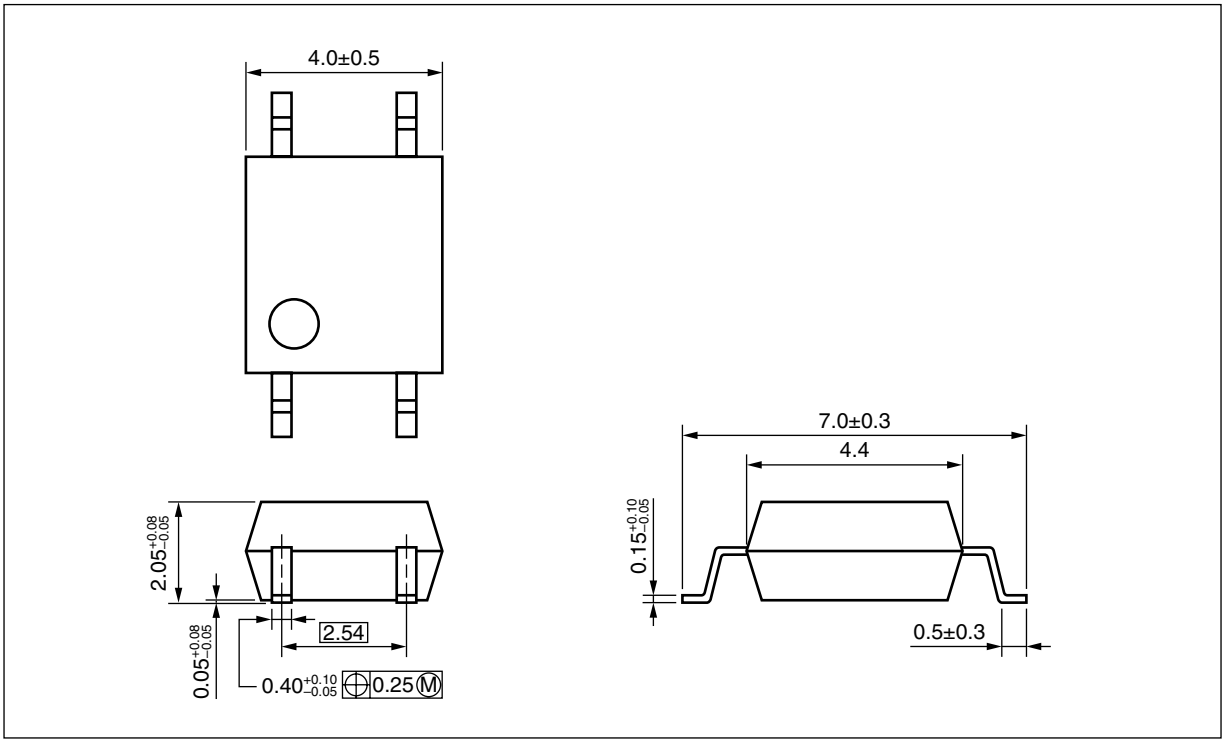
- Laptop PC, PDA
- Modem card
- Telephone, FAX
- Measurement equipment

Document No. PN10459EJ03V0DS (3rd edition)
Date Published October 2008 NS
Printed in Japan

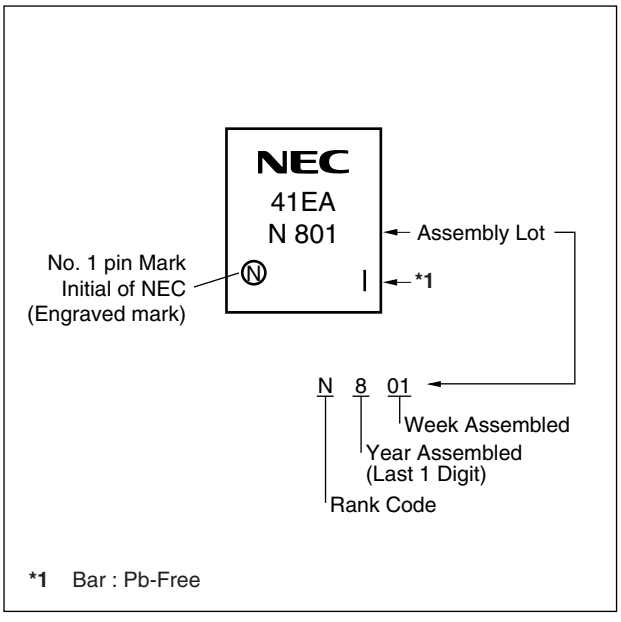
The mark <R> shows major revised points.

The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

PACKAGE DIMENSIONS (UNIT: mm)



<R> **MARKING EXAMPLE**



***1** Bar : Pb-Free

<R> **ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS7241E-1A	PS7241E-1A-A	Pb-Free	Magazine case 100 pcs	Standard products (UL, BSI approved)	PS7241E-1A
PS7241E-1A-E3	PS7241E-1A-E3-A		Embossed Tape 900 pcs/reel		
PS7241E-1A-E4	PS7241E-1A-E4-A				
PS7241E-1A-F3	PS7241E-1A-F3-A		Embossed Tape 3 500 pcs/reel		
PS7241E-1A-F4	PS7241E-1A-F4-A				

***1** For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I_F	50	mA
	Reverse Voltage	V_R	5.0	V
	Power Dissipation	P_D	50	mW
	Peak Forward Current*1	I_{FP}	1	A
MOS FET	Break Down Voltage	V_L	400	V
	Continuous Load Current	I_L	120	mA
	Pulse Load Current*2 (AC/DC Connection)	I_{LP}	240	mA
	Power Dissipation	P_D	300	mW
Isolation Voltage*3		BV	1 500	Vr.m.s.
Total Power Dissipation		P_T	350	mW
Operating Ambient Temperature		T_A	–40 to +85	°C
Storage Temperature		T_{stg}	–40 to +100	°C

***1** PW = 100 μs, Duty Cycle = 1%

***2** PW = 100 ms, 1 shot

***3** AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.
Pins 1-2 shorted together, 3-4 shorted together.

RECOMMENDED OPERATING CONDITIONS (T_A = 25°C)

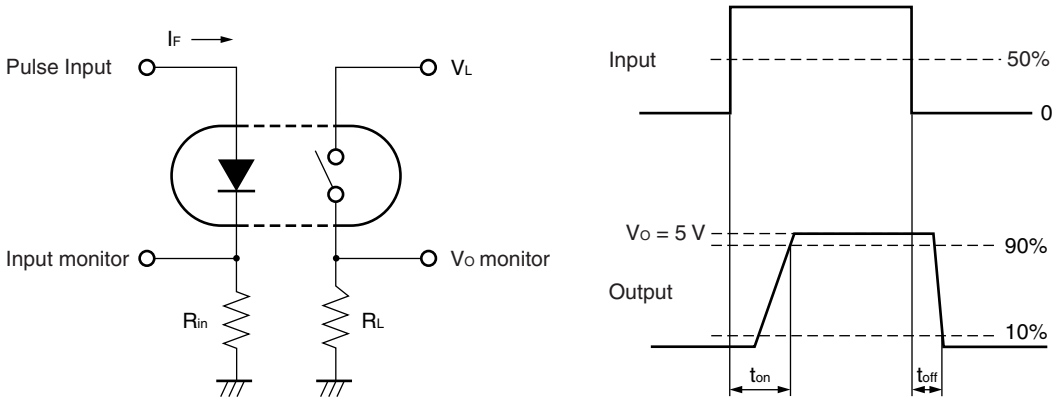
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I_F	4	10	20	mA
LED Off Voltage	V_F	0		0.5	V

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

<R>

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	I_F = 10 mA		1.2	1.4	V
	Reverse Current	I_R	V_R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I_{Loff}	V_D = 400 V			1.0	μA
	Output Capacitance	C_{out}	V_D = 0 V, f = 1 MHz		18		pF
Coupled	LED On-state Current	I_{Fon}	I_L = 120 mA			4.0	mA
	On-state Resistance	R_{on1}	I_F = 10 mA, I_L = 10 mA		22	35	Ω
		R_{on2}	I_F = 10 mA, I_L = 120 mA, t ≤ 10 ms		17	23	
	Turn-on Time*1, 2	t_{on}	I_F = 10 mA, V_O = 5 V, R_L = 500 Ω, PW ≥ 10 ms		0.5	1.0	ms
	Turn-off Time*1, 2	t_{off}			0.07	0.2	
	Isolation Resistance	R_{I-O}	V_{I-O} = 1.0 kV_{DC}	10^9			Ω
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1 MHz		0.5		pF

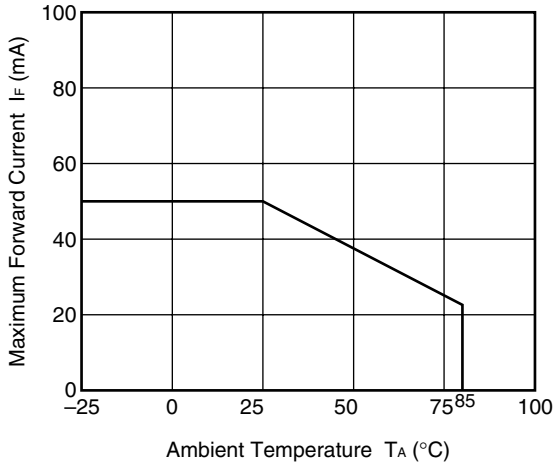
***1** Test Circuit for Switching Time



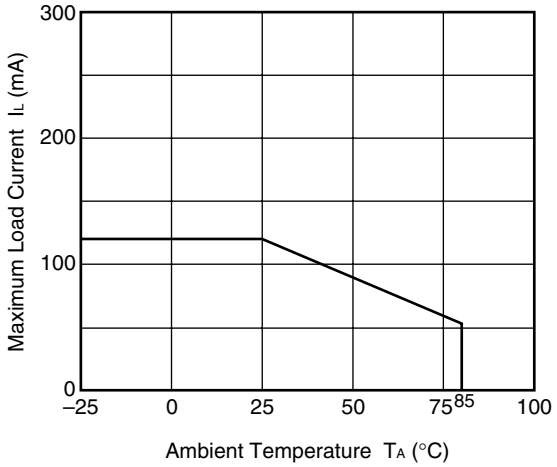
***2** The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS (T_A = 25°C, unless otherwise specified)

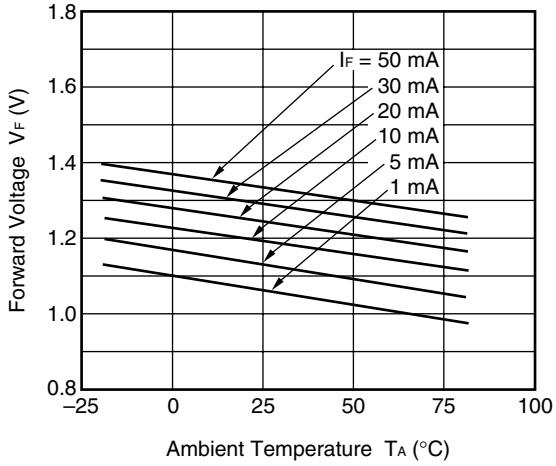
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



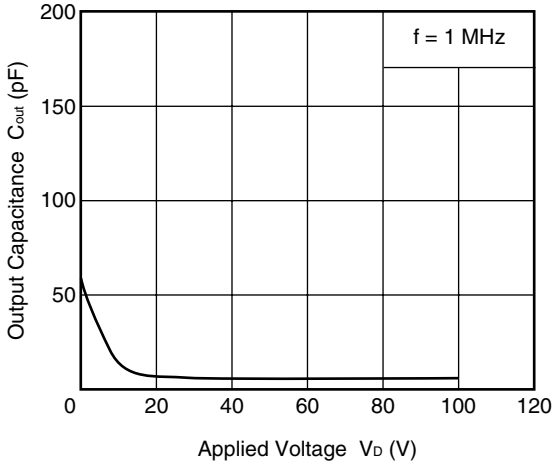
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



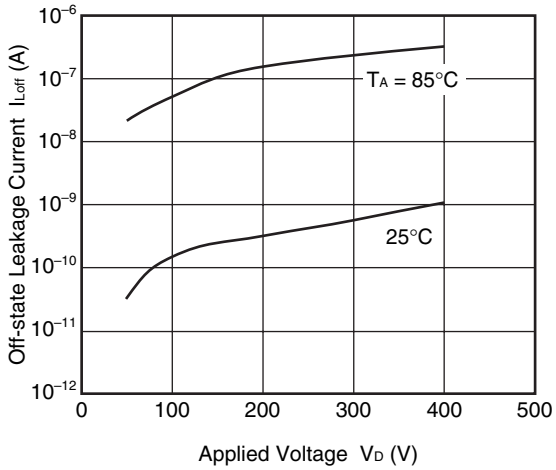
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



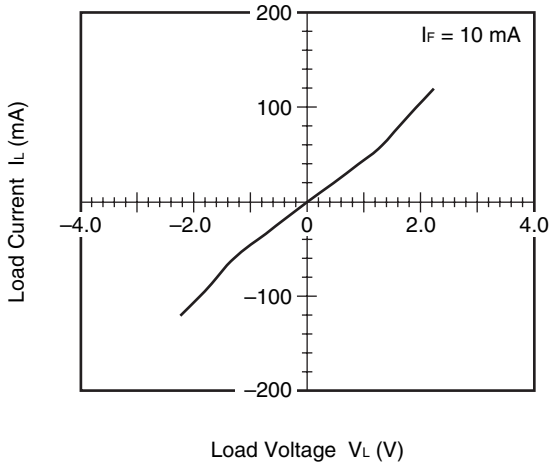
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE

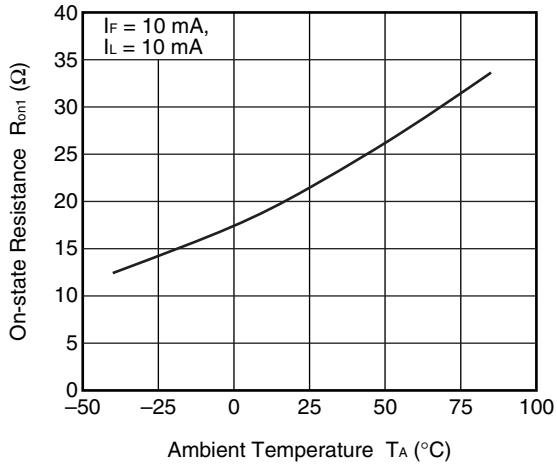


LOAD CURRENT vs. LOAD VOLTAGE

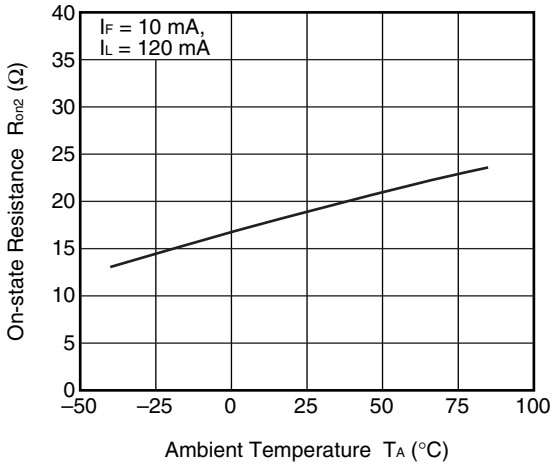


Remark The graphs indicate nominal characteristics.

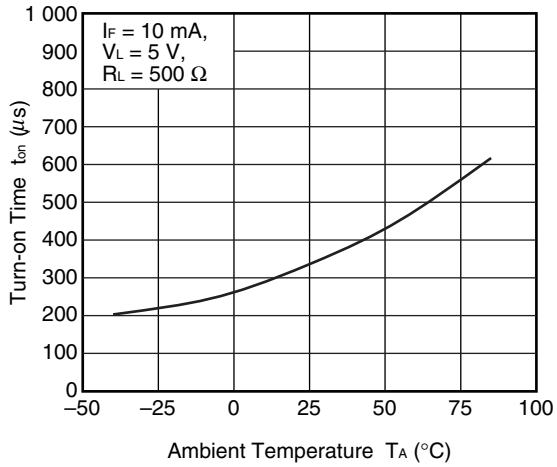
ON-STATE RESISTANCE vs.
AMBIENT TEMPERATURE



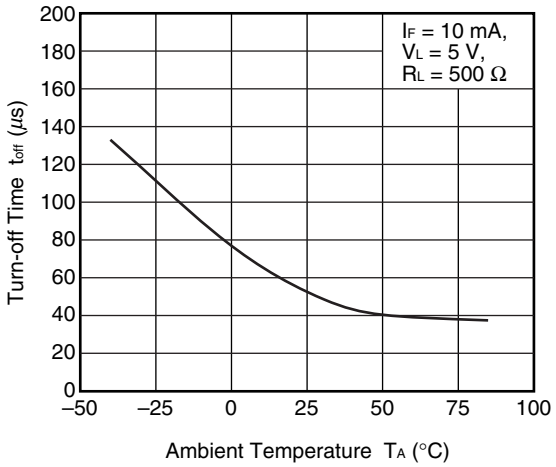
ON-STATE RESISTANCE vs.
AMBIENT TEMPERATURE



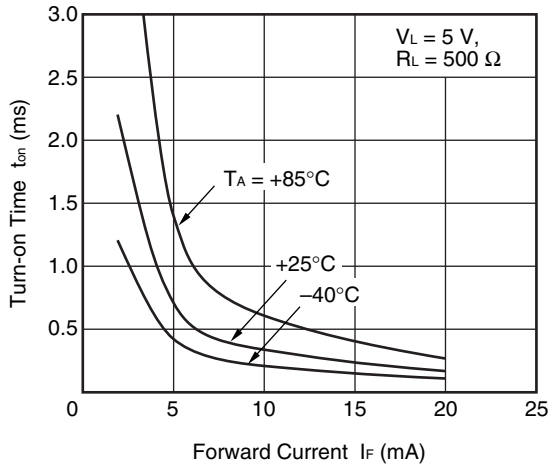
TURN-ON TIME vs.
AMBIENT TEMPERATURE



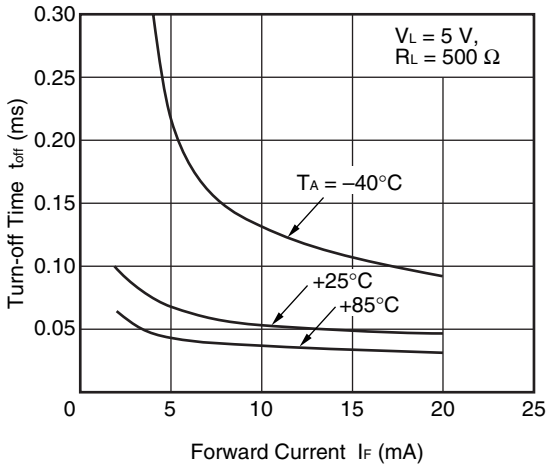
TURN-OFF TIME vs.
AMBIENT TEMPERATURE



TURN-ON TIME vs. FORWARD CURRENT

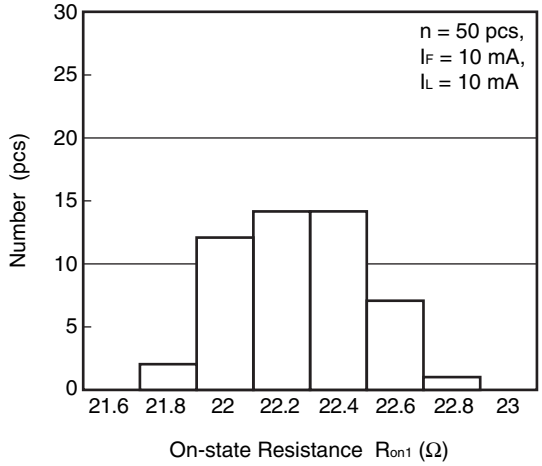


TURN-OFF TIME vs. FORWARD CURRENT

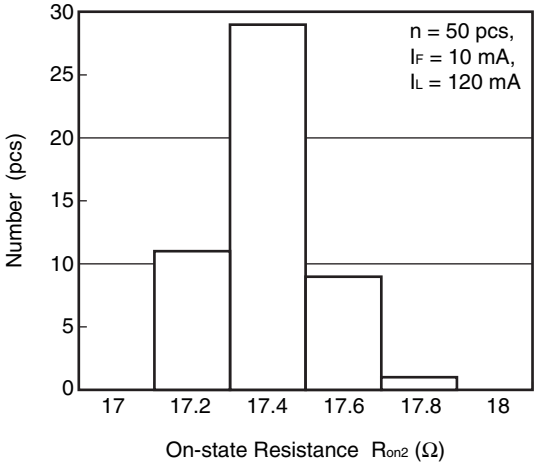


Remark The graphs indicate nominal characteristics.

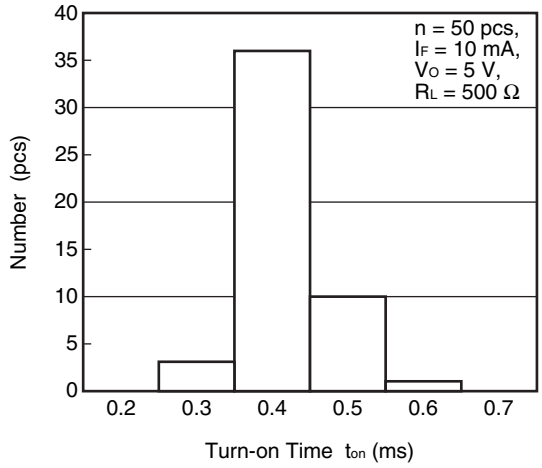
ON-STATE RESISTANCE DISTRIBUTION



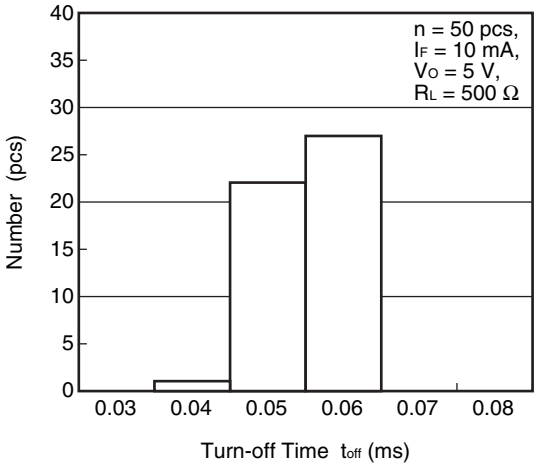
ON-STATE RESISTANCE DISTRIBUTION



TURN-ON TIME DISTRIBUTION



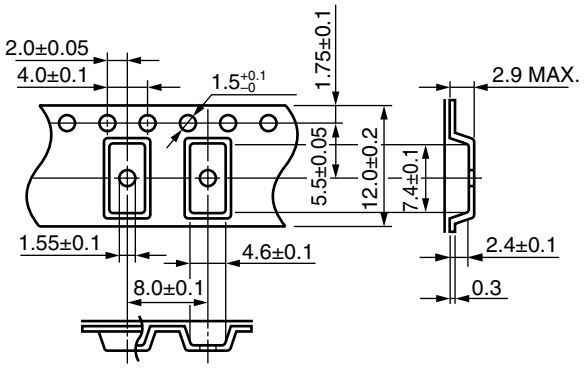
TURN-OFF TIME DISTRIBUTION



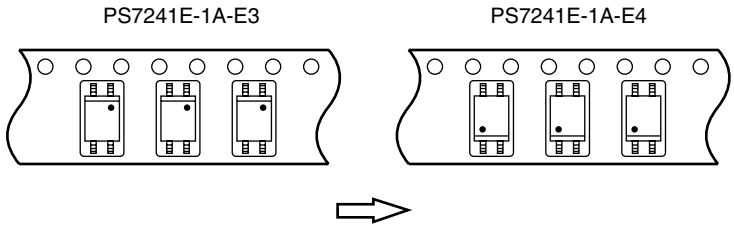
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (in millimeters)

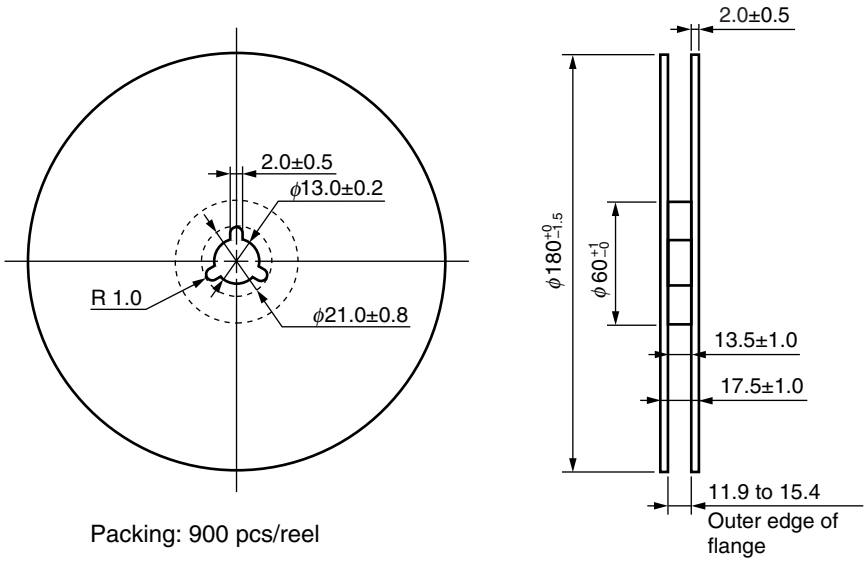
Outline and Dimensions (Tape)



Tape Direction

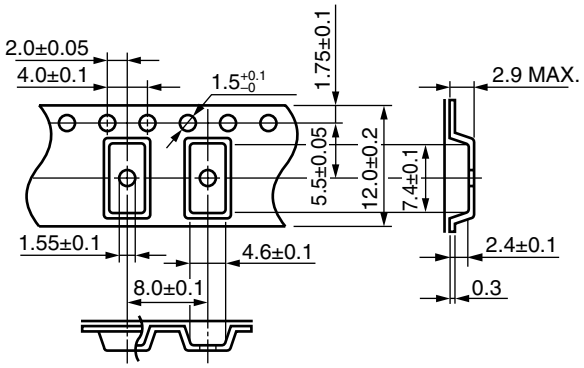


Outline and Dimensions (Reel)

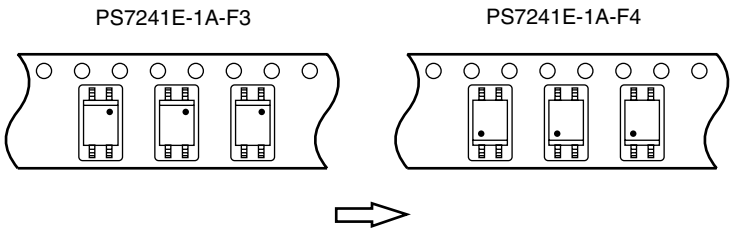


Packing: 900 pcs/reel

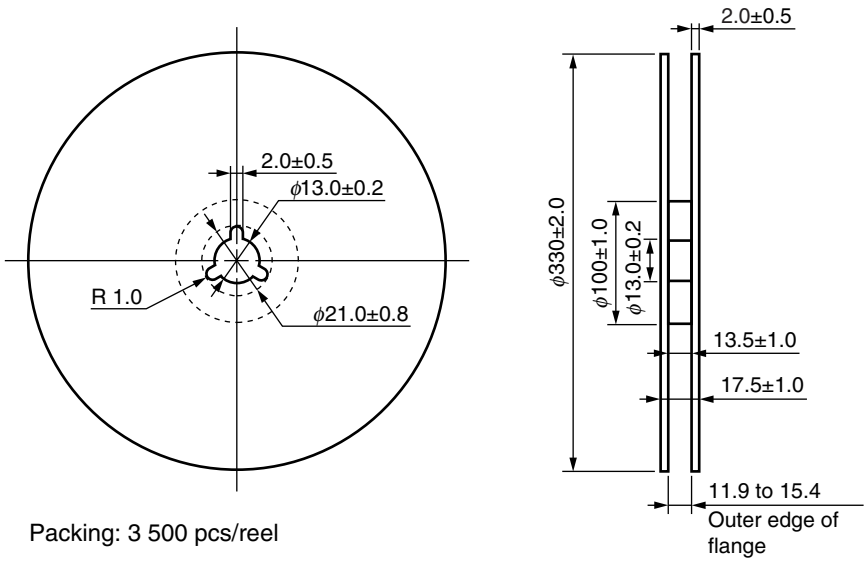
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



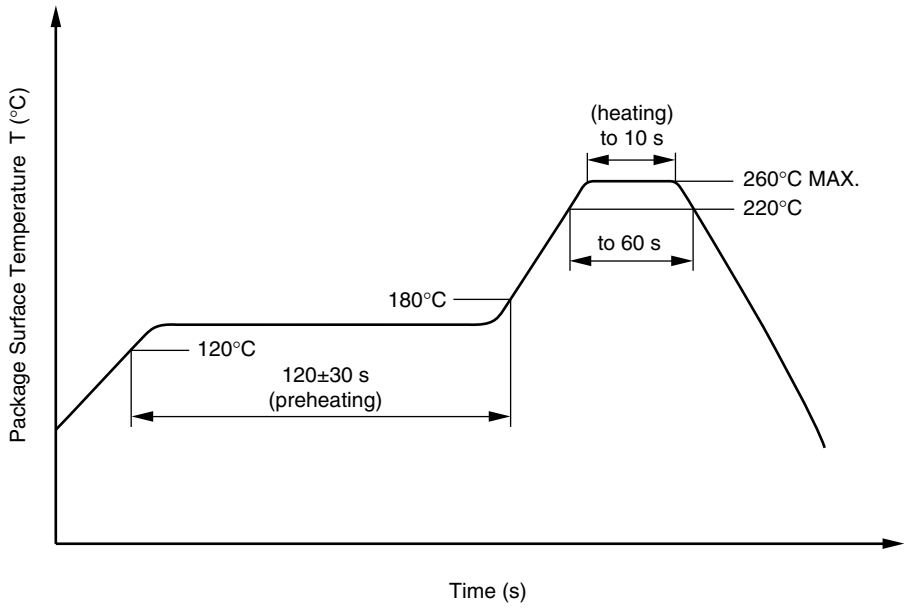
Packing: 3 500 pcs/reel

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

• Peak reflow temperature	260°C or below (package surface temperature)
• Time of peak reflow temperature	10 seconds or less
• Time of temperature higher than 220°C	60 seconds or less
• Time to preheat temperature from 120 to 180°C	120±30 s
• Number of reflows	Three
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature	260°C or below (molten solder temperature)
• Time	10 seconds or less
• Preheating conditions	120°C or below (package surface temperature)
• Number of times	One
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

<R> **(3) Soldering by soldering iron**

• Peak temperature (lead part temperature)	350°C or below
• Time (each pins)	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> **USAGE CAUTIONS**

1. Protect against static electricity when handling.

2. Avoid storage at a high temperature and high humidity.

- **The information in this document is current as of October, 2008. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC Electronics data sheets or data books, etc., for the most up-to-date specifications of NEC Electronics products. Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.**
- No part of this document may be copied or reproduced in any form or by any means without the prior written consent of NEC Electronics. NEC Electronics assumes no responsibility for any errors that may appear in this document.
- NEC Electronics does not assume any liability for infringement of patents, copyrights or other intellectual property rights of third parties by or arising from the use of NEC Electronics products listed in this document or any other liability arising from the use of such products. No license, express, implied or otherwise, is granted under any patents, copyrights or other intellectual property rights of NEC Electronics or others.
- Descriptions of circuits, software and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software and information in the design of a customer's equipment shall be done under the full responsibility of the customer. NEC Electronics assumes no responsibility for any losses incurred by customers or third parties arising from the use of these circuits, software and information.
- While NEC Electronics endeavors to enhance the quality, reliability and safety of NEC Electronics products, customers agree and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize risks of damage to property or injury (including death) to persons arising from defects in NEC Electronics products, customers must incorporate sufficient safety measures in their design, such as redundancy, fire-containment and anti-failure features.
- NEC Electronics products are classified into the following three quality grades: "Standard", "Special" and "Specific".

  The "Specific" quality grade applies only to NEC Electronics products developed based on a customer-designated "quality assurance program" for a specific application. The recommended applications of an NEC Electronics product depend on its quality grade, as indicated below. Customers must check the quality grade of each NEC Electronics product before using it in a particular application.

  "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots.

  "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).

  "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC Electronics products is "Standard" unless otherwise expressly specified in NEC Electronics data sheets or data books, etc. If customers wish to use NEC Electronics products in applications not intended by NEC Electronics, they must contact an NEC Electronics sales representative in advance to determine NEC Electronics' willingness to support a given application.

(Note)

(1) "NEC Electronics" as used in this statement means NEC Electronics Corporation and also includes its majority-owned subsidiaries.

(2) "NEC Electronics products" means any product developed or manufactured by or for NEC Electronics (as defined above).

M8E 02. 11-1

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.